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Renesas Electronics website: http://www.renesas.com

April 1<sup>st</sup>, 2010 Renesas Electronics Corporation

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### DATA SHEET

## RENESAS

## SILICON POWER TRANSISTOR Phase-out/Discontinued 2SC3569

NPN SILICON TRIPLE DIFFUSED TRANSISTOR FOR HIGH-VOLTAGE HIGH-SPEED SWITCHING

The 2SC3569 is a mold power transistor developed for highvoltage high-speed switching, and is ideal for use in drivers such as switching regulators, DC/DC converters, and high-frequency power amplifiers.

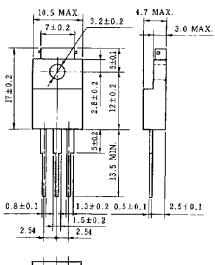
#### FEATURES

- Mold package that does not require an insulating board or insulation bushing
- Low collector saturation voltage: VCE(sat) = 1.0 V MAX. (@ 0.7 A)
- Fast switching speed: t<sub>f</sub> ≤ 1.0 μs MAX. (@ 0.7 A)
- Wide base reverse-bias SOA: VCEX(SUS) = 450 V MIN. (@ 0.5 A)

| Parameter                    | Symbol         | Ratings     | Unit |  |  |  |  |
|------------------------------|----------------|-------------|------|--|--|--|--|
| Collector to base voltage    | Vсво           | 500         | V    |  |  |  |  |
| Collector to emitter voltage | VCEO           | 400         | V    |  |  |  |  |
| Emitter to base voltage      | Vebo           | 7.0         | V    |  |  |  |  |
| Collector current (DC)       | IC(DC)         | 2.0         | А    |  |  |  |  |
| Collector current (pulse)    | IC(pulse)*     | 4.0         | А    |  |  |  |  |
| Base current (DC)            | B(DC)          | 1.0         | А    |  |  |  |  |
| Total power dissipation      | P⊤ (Tc = 25°C) | 15          | W    |  |  |  |  |
| Total power dissipation      | P⊤ (Ta = 25°C) | 2.0         | W    |  |  |  |  |
| Junction temperature         | Tj             | 150         | °C   |  |  |  |  |
| Storage temperature          | Tstg           | -55 to +150 | °C   |  |  |  |  |

#### ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

#### PACKAGE DRAWING (UNIT: mm)





Electrode Connection

- 1. Base
- 2. Collector
- 3. Emitter

\* PW  $\leq$  300  $\mu$ s, duty cycle  $\leq$  10%

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#### ELECTRICAL CHARACTERISTICS (Ta = 25°C)

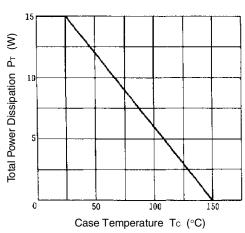
| Parameter                    | Symbol                 | Conditions   | MIN. | TYP. | MAX. | Unit |
|------------------------------|------------------------|--|------|------|------|------|
| Collector to emitter voltage | VCEO(SUS)              | Ic = 0.5 A, Iв1 = 0.1 A, L = 1 mH  | 400  |      |      | V    |
| Collector to emitter voltage | VCEX(SUS)1             |  |      |      |      | V    |
| Collector to emitter voltage | VCEX(SUS)2             | Ic = 1.0 A, I <sub>B1</sub> = 0.2 A, $-I_{B2}$ = 0.1 A,<br>L = 180 $\mu$ H, clamped                | 400  |      |      | V    |
| Collector cutoff current     | Ісво                   | $V_{CB} = 400 \text{ V}, \text{ I}_{E} = 0$  |      |      | 10   | μA   |
| Collector cutoff current     | ICER                   | V <sub>CE</sub> = 400 V, R <sub>BE</sub> = 51 Ω, Ta = 125°C  |      |      | 1.0  | mA   |
| Collector cutoff current     | ICEX1                  | Vce = 400 V, Vbe(off) = -1.5 V   |      |      | 10   | μA   |
| Collector cutoff current     | ICEX2                  | $V_{CE} = 400 \text{ V}, \text{ V}_{BE(OFF)} = -1.5 \text{ V},$<br>Ta = 125°C                      |      |      | 1.0  | mA   |
| Emitter cutoff current       | Іево                   | V <sub>EB</sub> = 5.0 V, Ic = 0  |      |      | 10   | μA   |
| DC current gain              | hfe1*                  | Vce = 5.0 V, Ic = 0.2 A  | 20   |      | 80   |      |
| DC current gain              | hFE2*                  | Vce = 5.0 V, Ic = 0.5 A  | 10   |      |      |      |
| Collector saturation voltage | V <sub>CE(sat)</sub> * | Ic = 0.7 A, Iв = 0.14 A  |      |      | 1.0  | V    |
| Base saturation voltage      | V <sub>BE(sat)</sub> * | Ic = 0.7 A, Iв = 0.14 A  |      |      | 1.2  | V    |
| Turn-on time                 | ton                    | $I_{C} = 0.7 \text{ A}, \text{ R}_{L} = 214 \Omega,$   |      |      | 1.0  | μs   |
| Storage time                 | tstg                   | $I_{B1} = -I_{B2} = 0.14 \text{ A}, \text{ Vcc} \cong 150 \text{ V}$<br>Refer to the test circuit. |      |      | 2.5  | μs   |
| Fall time                    | tr                     |  |      |      | 1.0  | μs   |

\* Pulse test PW  $\leq$  350  $\mu$ s, duty cycle  $\leq$  2%

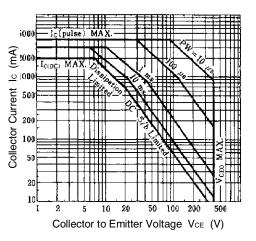
#### **hfe CLASSIFICATION**

| Marking | М        | L        | К        |
|---------|----------|----------|----------|
| HFE1    | 20 to 40 | 30 to 60 | 40 to 80 |

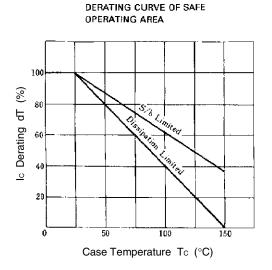
#### **TYPICAL CHARACTERISTICS (Ta = 25°C)**

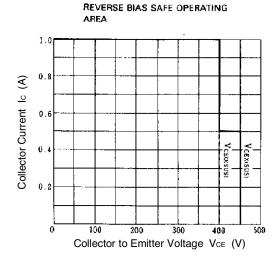


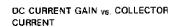
TOTAL POWER DISSIPATION VS. CASE TEMPERATURE FORWARD BIAS SAFE OPERATING AREA

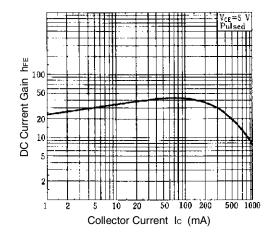


# Phase-out/Discontinued

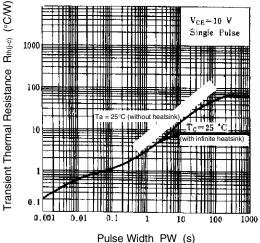






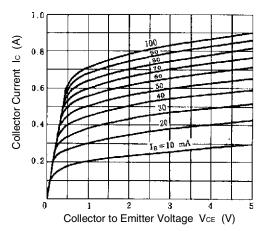


TRANSIENT THERMAL RESISTANCE

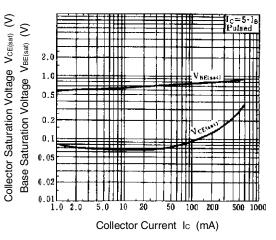


Puise Width PW (s)

COLLECTOR CURRENT VS. COLLECTOR TO EMITTER VOLTAGE



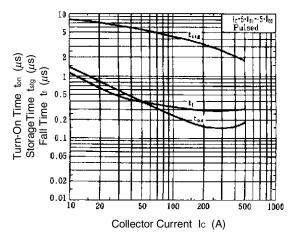
BASE AND COLLECTOR SATURATION VOLTAGE VS. COLLECTOR CURRENT



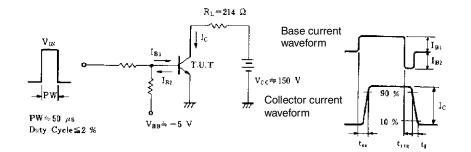
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TURN ON TIME, STORAGE TIME AND FALL TIME VS. COLLECTOR CURRENT



SWITCHING TIME  $(t_{\text{on}}, t_{\text{stg}}, t_{\text{f}})$  TEST CIRCUIT



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# Phase-out/Discontinued

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